

REMARKS

Claims 1-21 are pending in this application. By this Amendment, Applicants amend the specification and claims 1 and 13.

The drawings were objected to because reference character "17" has been used to designate both an external electrode and a chip electronic component. Applicants have amended the first full paragraph on page 19 of the specification to properly refer to the external electrodes as "18 to 20" as opposed to "17 to 19" as originally filed.

The drawings have further been objected to for allegedly no mentioning reference signs 12 and 13a. These reference signs are mentioned in the specification on page 16 at lines 14 and 22, respectively.

Additionally, the drawings have been objected to for failing to show every feature of the invention specified in the claims (particularly the printed circuit board recited in claim 13). Applicants have amended claim 13 to remove positive recitations of the circuit board.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the objections to the drawings.

Claims 1, 2, 6-12, 14-18, 20 and 21 were rejected under 35 U.S.C. § 102(b) as being anticipated by Kaida et al. (U.S. 5,627,425). And claims 3-5, 13 and 19 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Kaida et al. in view of Okamura (U.S. 5,892,415). These rejection are respectfully traversed.

Claim 1 recites:

"a circuit; an electronic component element having a lower surface and a pair of side surfaces; and a plurality of external electrodes arranged to extend over the lower surface and at least one of the side surfaces of said electronic component element and electrically connected to the circuit therein; wherein **said each external electrode portion provided on the lower surface of the electronic component element is provided with a narrow portion and a wide portion.**" (Emphasis added).

Claim 14 recites similar elements as recited in claim 1, including the emphasized elements.

The Examiner alleges that "Kaida et al. discloses a circuit having a lower surface,

a pair of side surfaces, a plurality of external electrodes 117, 118 and external electrode portions provided on the lower surface of the electric component with a narrow portion and a wide portion (see figure 38). . . . Moreover, the width of the external electrode portion on the lower surface of the electronic component element is larger than the width of the external electrode portion formed on the side surface of the electronic component element (see figure 39)." Applicants disagree.

Initially, as is clear from the Examiner's description of the teachings of Kaida et al., the Examiner has ignored elements recited in claims 1 and 14. Particularly, claims 1 and 14 recite that "said each external electrode portion provided on the lower surface of the electronic component element is provided with a narrow portion and a wide portion". The Examiner failed to address this recited feature in the prior art rejections of the claims.

The fact that Fig. 39 of Kaida illustrates "the width of the electrode portion on the lower surface of the electronic element is larger than the width of the electrode portion formed on the side surface of the electronic component element" is irrelevant to the claimed invention, and clearly does not anticipate the claimed invention. Kaida et al. clearly fails to teach or suggest electrode portions provided on the lower surface of the electronic component element are provided with a narrow portion and a wide surface. The electrode portions on the lower surface of the electronic component element of Kaida et al. are clearly all the same width. In every embodiment, including Figs. 38 and 39, the external electrodes have a consistent width across the entire lower surface of the electronic component element.

Therefore, Applicants respectfully submit that Kaida et al. fails to teach or suggest the claimed combination of elements and unique arrangement thereof recited in claims 1 and 14.

In view of the foregoing, Applicants respectfully submit that claims 1 and 14 are allowable. Claims 2-13 and 15-21 are dependent upon claims 1 and 14, respectively, and are therefore allowable for at least the reasons that claims 1 and 14 are allowable.

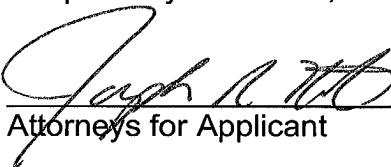
In view of the foregoing Remarks, Applicants respectfully submit that this

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application is in condition for allowance. Favorable consideration and prompt allowance are respectfully solicited.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,



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VERSION WITH MARKINGS SHOWING CHANGES MADE

In the Specification:

Therefore, as in the chip electronic component 1 of the first preferred embodiment, the external electrodes [17 to 19] 18 to 20 have narrow portions and wide portions respectively, formation of solder fillets is prevented and thereby the mounting density is substantially increased, and the bonding stability is substantially improved when mounted onto the printed circuit board.

In the Claims:

1. A chip electronic component comprising:
a circuit;
an electronic component element having a lower surface and a pair of side surfaces; and
a plurality of external electrodes arranged to extend over the lower surface and at least one of the side surfaces of said electronic component element and electrically connected to the circuit therein; wherein
said each external electrode portion provided on the lower surface of the [electric] electronic component element is provided with a narrow portion and a wide portion.

13. A mounting structure of a chip electronic component according to claim 1 [comprising a chip electronic component] to be mounted on [said] a printed circuit board via a conductive bond [according to claim 1], wherein [the] a bonding [bonded] portion defined by a conductive bond is located inside of the outer periphery of the chip electronic component as seen from the top of the chip electronic component.